## Rochester Electronics

## SMD, QML, MIL-STD-883 FLOWS

**SMD/QML**: Devices are processed per the applicable Class Q requirements of MIL-PRF-38535 and the SMD detail requirements and are fully compliant as such.

MIL-STD-883: Devices are tested 100% electrically at -55°C, +25°C, and +125°C per applicable manufacturer's part number datasheet or test program and processed per MIL-STD-883 and are fully compliant as such.

\*Performed at Rochester's Newburyport campus when appropriate. \*\*Performed at Rochester's Newburyport campus.

## START

- > \*\*WAFER TRACEABILITY and DESIGN VERIFICATION (MIL-STD-883/QML)
- > \*\*OUTGOING QAINSPECT
- \*ASSEMBLY HOUSE INCOMING QAINSPECT
- \*WAFER SAW and DIE PREP
- > \*SECOND OPTICAL INSPECTION
- > \*QALOTACCEPTANCE
- > \*FRAME ATTACH
- > \*DIE ATTACH
- > \*DIE ATTACH CURE
- > \*WIRE BOND
- > \*THIRD OPTICAL INSPECTION
- > \*QALOTACCEPTANCE
- \*Rochester FIELD SOURCE SURVEILLANCE LOT ACCEPTANCE (optional)
- > \*PRE-SEAL BAKE and VACUUM PRE-WELD BAKE (TO type package only)
- > \*HERMETIC SEAL/WELD

- \*TEMPERATURE CYCLING
- > \*CONSTANT ACCELERATION
- > \*LEAD TRIM (if applicable)
- > \*SOLDER DIP LEAD FINISH and INSPECTION
- \*MARK and CURE (optional sequence)
- > \*FINE LEAK SEAL TEST
- > \*GROSS LEAK SEAL TEST
- \* VISUAL and PACKAGE LOAD
- > \*QALOTACCEPTANCE
- > \*SHIP
- > \*\*INCOMING QA LOT ACCEPTANCE

- \*\*Test Lab INCOMING INSPECT
- > \*\*INITIAL ELECTRICAL TEST
- > \*\*BURNIN
- \*\*ELECTRICAL TEST INTERIM and FINAL
- > \*\*QUALITY CONFORMANCE INSPECTION Group A
- > \*\*FINE/GROSS LEAK
- > \*\*EXTERNAL VISUAL
- > \*\*QUALITY CONFORMANCE INSPECTION (Groups B, C, and D)
- > \*\*FINAL QA LOT ACCEPTANCE

**FINISH** 

## **ROCHESTER ELECTRONICS, LLC**

WORLDWIDE CORPORATE HEADQUARTERS

16 Malcolm Hoyt Drive – Newburyport, Massachusetts 01950 USA

978.462.9332 phone – 978.462.9512 fax

sales@rocelec.com

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